



*micro*Power, Single-Supply, CMOS Instrumentation Amplifier

FEATURES

- LOW QUIESCENT CURRENT: 40μA/channel Shut Down: < 1μA
- HIGH GAIN ACCURACY: G = 5, 0.02%, 2ppm/°C
- GAIN SET WITH EXTERNAL RESISTORS
- LOW OFFSET VOLTAGE: ±200µV
- HIGH CMRR: 94dB
- LOW BIAS CURRENT: 10pA
- BANDWIDTH: 500kHz, G = 5V/V
- RAIL-TO-RAIL OUTPUT SWING: (V+) 0.02V
- WIDE TEMPERATURE RANGE: -55°C to +125°C
- SINGLE VERSION IN MSOP-8 PACKAGE AND DUAL VERSION IN TSSOP-14 PACKAGE

DESCRIPTION

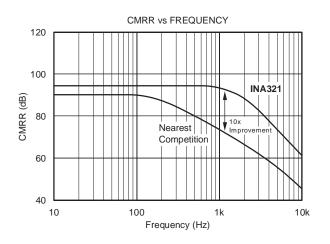
The INA321 family is a series of rail-to-rail output, micropower CMOS instrumentation amplifiers that offer wide-range, single-supply, as well as bipolar-supply operation. The INA321 family provides low-cost, low-noise amplification of differential signals with micropower current consumption of 40 μ A. When shutdown, the INA321 has a quiescent current of less than 1 μ A. Returning to normal operations within microseconds, the shutdown feature makes the INA321 optimal for low-power battery or multiplexing applications.

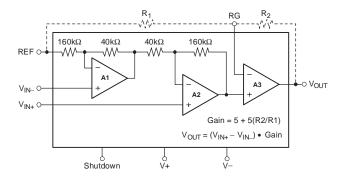
Configured internally for 5V/V gain, the INA321 offers exceptional flexibility with user-programmable external gain resistors. The INA321 reduces common-mode error over frequency and with CMRR remaining high up to 3kHz, line noise and line harmonics are rejected.

The low-power design does not compromise on bandwidth or slew rate, making the INA321 ideal for driving sample Analog-to-Digital (A/D) converters as well as general-purpose applications. With high precision, low cost, and small packaging, the INA321 outperforms discrete designs, while offering reliability and performance.

APPLICATIONS

- INDUSTRIAL SENSOR AMPLIFIERS: Bridge, RTD, Thermistor, Position
- PHYSIOLOGICAL AMPLIFIERS: ECG, EEG, EMG
- A/D CONVERTER SIGNAL CONDITIONING
- DIFFERENTIAL LINE RECEIVERS WITH GAIN
- FIELD UTILITY METERS
- PCMCIA CARDS
- COMMUNICATION SYSTEMS
- TEST EQUIPMENT
- AUTOMOTIVE INSTRUMENTATION

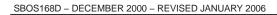




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ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Supply Voltage, V+ to V 7.5\
Signal Input Terminals Voltage ⁽²⁾ $(V-) - (0.5V)$ to $(V+) + (0.5V)$
Current ⁽²⁾ 10mA
Output Short-Circuit ⁽³⁾ Continuous
Operating Temperature65°C to +150°C
Storage Temperature65°C to +150°C
Junction Temperature+150°C

- (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not supported.
- (2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current limited to 10mA or less.
- (3) Short-circuit to ground, one amplifier per package.

PACKAGE/ORDERING INFORMATION⁽¹⁾



ELECTROSTATIC DISCHARGE SENSITIVITY

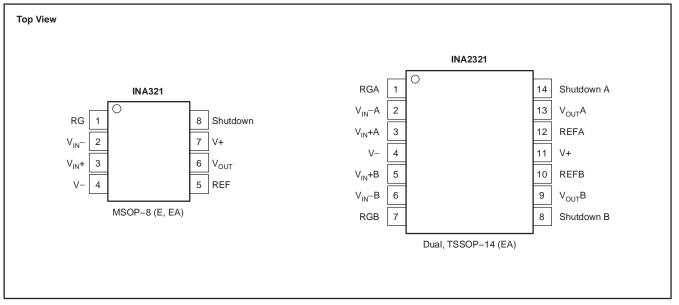
This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PRODUCT	T PACKAGE-LEAD PACKAGE SPECIFIED DESIGNATOR RANGE		PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY				
SINGLE									
INA321E	MSOP-8	DGK	–55°C to +125°C	C21	INA321E/250	Tape and Reel, 250			
"	"	"	"	"	INA321E/2K5	Tape and Reel, 2500			
INA321EA	MSOP-8	DGK	–55°C to +125°C	C21	INA321EA/250	Tape and Reel, 250			
"	"	"	"	"	INA321EA/2K5	Tape and Reel, 3000			
DUAL									
INA2321EA	TSSOP-14	PW	–55°C to +125°C	INA2321EA	INA2321EA/250	Tape and Reel, 250			
"	"	"	"	"	INA2321EA/2K5	Tape and Reel, 2500			

(1) For the most current package and ordering information, see the Package Option Addendum located at the end of this data sheet.

PIN CONFIGURATIONS



ELECTRICAL CHARACTERISTICS: V_S = +2.7V to +5.5V

BOLDFACE limits apply over the specified temperature range, $T_A = -55^{\circ}C$ to $+125^{\circ}C$.

At $T_A = +25^{\circ}C$, $R_L = 25k\Omega$, G = 25, and I_A common = $V_S/2$, unless otherwise noted.

				INA321E			INA321EA NA2321EA		
PARAMETER		CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
INPUT									
Input Offset Voltage, RTI		V _S = +5V		±0.2	±0.5		*	1	mV
Over Temperature	Vos				±2.2			2.5	mV
vs Temperature	dV _{OS} /dT			±7			*		μV/°C
vs Power Supply	PSRR	$V_{S} = +2.7V$ to +5.5V		±50	±200		*	*	μV/V
Over Temperature					±220			*	μV/V
Long-Term Stability				±0.4			*		μV/month
Input Impedance				10 ¹³ 3			*		$\Omega \parallel pF$
Input Common-Mode Rang	je	V _S = 2.7V	0.35		1.5	*		*	V
		V _S = 5V	0.55		3.8	*		*	V
Common-Mode Rejection	CMRR	$V_{S} = 5V, V_{CM} = 0.55V \text{ to } 3.8V$	90	94		80	*		dB
Over Temperature		V _S = 5V, V _{CM} = 0.55V to 3.8V	77			75			dB
		$V_{S} = 2.7V, V_{CM} = 0.35V \text{ to } 1.5V$		94			*		dB
Crosstalk, Dual				110			*		dB
INPUT BIAS CURRENT									
Bias Current	۱ _B			±0.5	±10		*	*	pА
Offset Current	los			±0.5	±10		*	*	pА
NOISE, RTI	e _n	R _S = 0Ω							
Voltage Noise: f = 10Hz				500			*		nV/√Hz
f = 100Hz				190			*		nV/√Hz
f = 1kHz				100			*		nV/√Hz
f = 0.1Hz to	10Hz			20			*		μVpp
Current Noise: f = 1kHz				3			*		fA/√Hz
GAIN ⁽¹⁾									
Gain Equation, Externally S	Set	G > 5		G = 5 + 5 (R2/R	1)		*		
Range of Gain			5		1000	*		*	V/V
Gain Error				±0.02	±0.1		*	*	%
vs Temperature		G = 5		±2	±10		*	*	ppm/°C
Nonlinearity		G = 25, V_S = 5V, V_O = 0.05 to 4.95	İ	±0.001	±0.010		*	*	% of FS
Over Temperature				±0.002	±0.015		*	*	% of FS
OUTPUT									
Output Voltage Swing from	Rail(2, 5)	G ≥ 10	50	25		*	*		mV
Over Temperature			50			*			mV
Capacitance Load Drive			See T	pical Characte	eristic(3)		*		pF
Short-Circuit Current	+ISC			8	1				
	-I _{SC}			16			*		mA

NOTE: * Specification is same as INA321E.

(1) Does not include errors from external gain setting resistors.

(2) Output voltage swings are measured between the output and power-supply rails.

(3) See typical characteristic Percent Overshoot vs Load Capacitance.

(4) See typical characteristic Shutdown Voltage vs Supply Voltage.

(5) Output does not swing to positive rail if gain is less than 10.



ELECTRICAL CHARACTERISTICS: V_S = +2.7V to +5.5V (continued)

BOLDFACE limits apply over the specified temperature range, $T_A = -55^{\circ}C$ to $+125^{\circ}C$.

At $T_A = +25^{\circ}C$, $R_L = 25k\Omega$, G = 25, and I_A common = $V_S/2$, unless otherwise noted.

				INA321E		-			
PARAMETER		CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
FREQUENCY RESPONSE									
Bandwidth, -3dB	BW	G = 5		500			*		kHz
Slew Rate	SR	$V_{S} = 5V, G = 25$		0.4			*		V/µs
Settling Time, 0.1%	tS	G = 5, C_L = 50pF, V_O = 2V step		8			*		μs
0.01%				12			*		μs
Overload Recovery		50% Input Overload G = 25		2			*		μs
POWER SUPPLY									
Specified Voltage Range			+2.7		+5.5	*		*	V
Operating Voltage Range				+2.5 to +5.5			*		V
Quiescent Current	lQ	per Channel, V _{SD} > 2.5 ⁽⁴⁾		40	60		*	*	μΑ
Over Temperature					70			*	μΑ
Shutdown Quiescent Current	ISD	per Channel, V _{SD} > 0.8 ⁽⁴⁾		0.01	1		*	*	μΑ
TEMPERATURE RANGE									
Specified Range			-55		+125	*		*	°C
Operating/Storage Range			-65		+150	*		*	°C
Thermal Resistance	$ heta_{JA}$	MSOP-8, TSSOP-14 Surface-Mount		150			*		°C/W

NOTE: * Specification is same as INA321E.

(1) Does not include errors from external gain setting resistors.

(2) Output voltage swings are measured between the output and power-supply rails.

(3) See typical characteristic Percent Overshoot vs Load Capacitance.

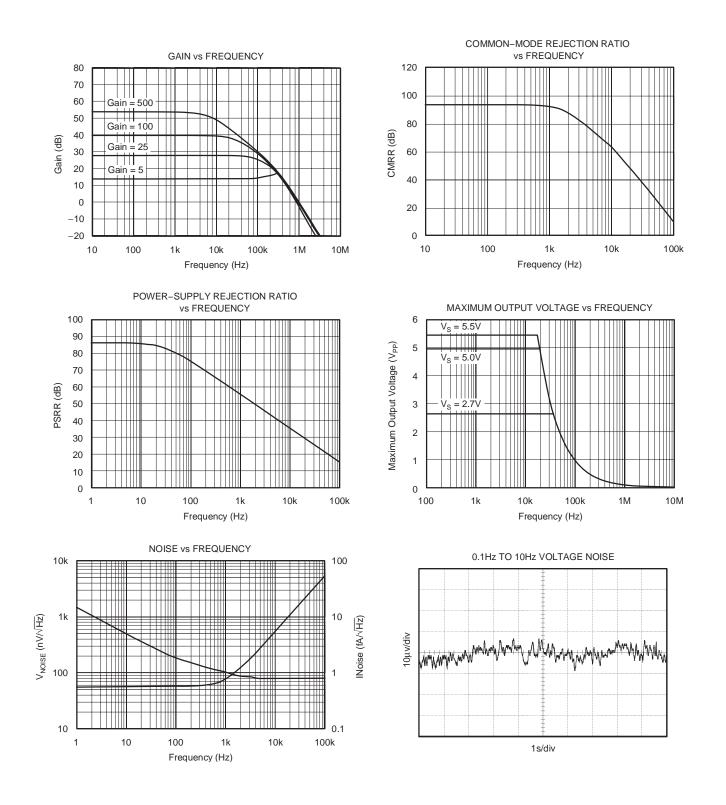
(4) See typical characteristic Shutdown Voltage vs Supply Voltage.

(5) Output does not swing to positive rail if gain is less than 10.

TYPICAL CHARACTERISTICS

STRUMENTS www.ti.com

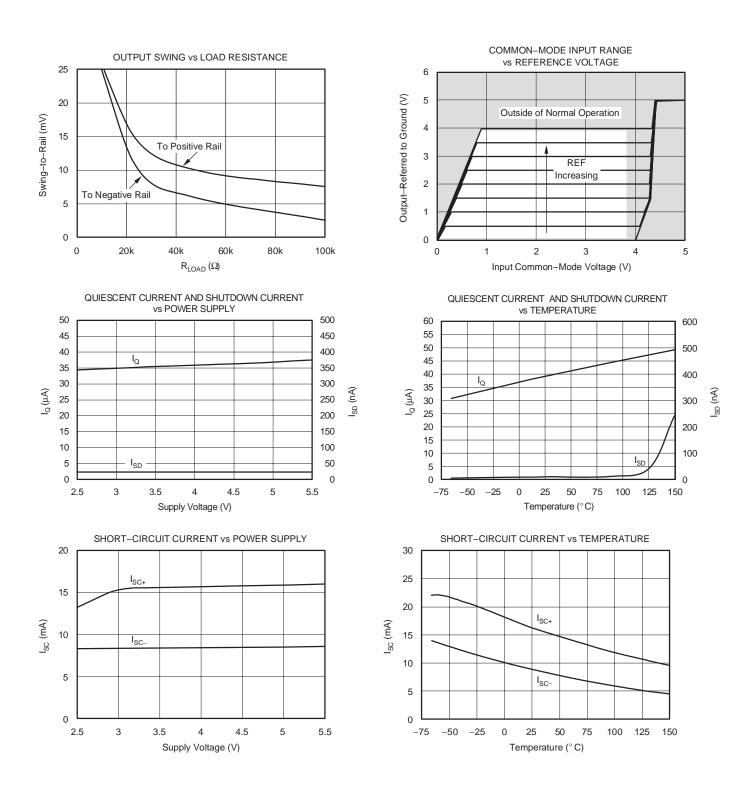
At T_A = +25°C, V_S = 5V, V_{CM} =1/2V_S, R_L = 25k Ω , and C_L = 50pF, unless otherwise noted.





TYPICAL CHARACTERISTICS (continued)

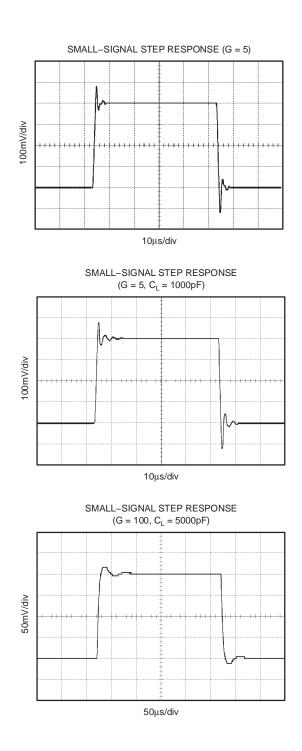
At T_A = +25°C, V_S = 5V, V_{CM} =1/2V_S, R_L = 25k Ω , and C_L = 50pF, unless otherwise noted.

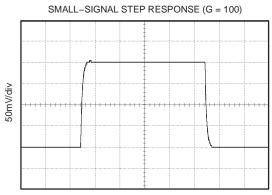




TYPICAL CHARACTERISTICS (continued)

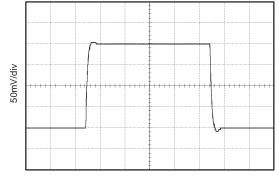
At T_A = +25°C, V_S = 5V, V_{CM} =1/2V_S, R_L = 25k Ω , and C_L = 50pF, unless otherwise noted.





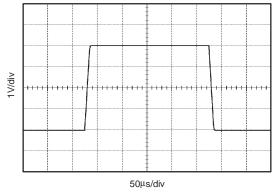
50µs/div

$$\label{eq:small-signal step response} \begin{split} \text{SMALL-SIGNAL STEP RESPONSE} \\ (\text{G} = 100, \, \text{C}_{\text{L}} = 1000 \text{pF}) \end{split}$$





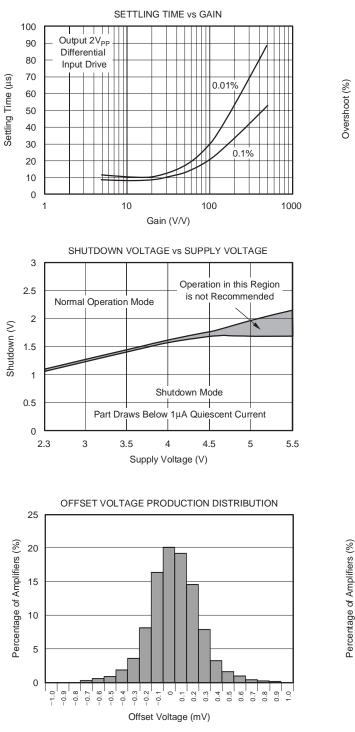
LARGE–SIGNAL STEP RESPONSE (G = 25, C_L = 50pF)

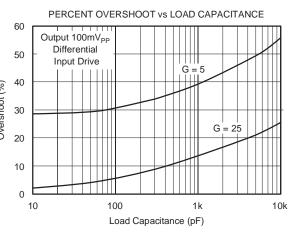


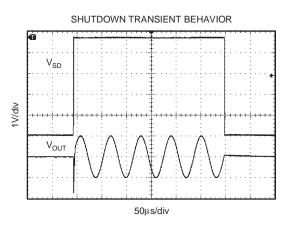


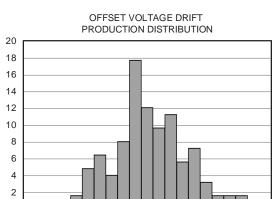
TYPICAL CHARACTERISTICS (continued)

At T_A = +25°C, V_S = 5V, V_{CM} =1/2V_S, R_L = 25k Ω , and C_L = 50pF, unless otherwise noted.









Offset Voltage Drift (µV/°C)

20_2

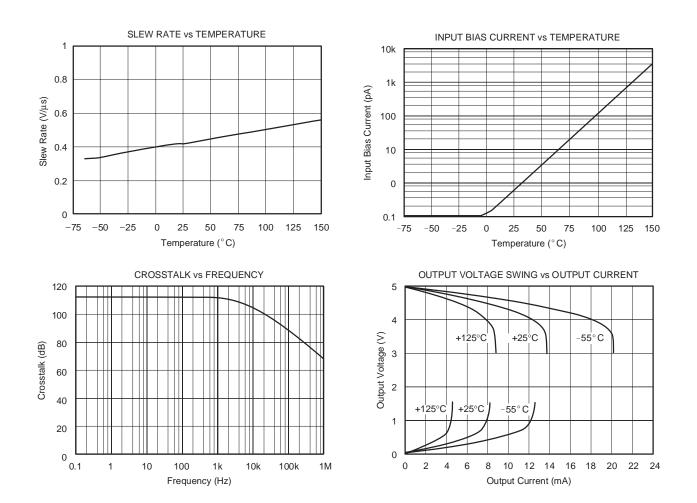
0

-20



TYPICAL CHARACTERISTICS (continued)

At T_A = +25°C, V_S = 5V, V_{CM} =1/2V_S, R_L = 25k Ω , and C_L = 50pF, unless otherwise noted.





APPLICATIONS INFORMATION

The INA321 is a modified version of the classic *two op amp* instrumentation amplifier, with an additional gain amplifier.

Figure 1 shows the basic connections for the operation of the INA321 and INA2321. The power supply should be capacitively decoupled with 0.1μ F capacitors as close to the INA321 as possible for noisy or high-impedance applications.

The output is referred to the reference terminal, which must be at least 1.2V below the positive supply rail.

OPERATING VOLTAGE

The INA321 family is fully specified over a supply range of +2.7V to +5.5V, with key parameters assured over the temperature range of -55° C to +125°C. Parameters that vary significantly with operating conditions, such as load conditions or temperature, are shown in the Typical Characteristics.

The INA321 may be operated on a single supply. Figure 2 shows a bridge amplifier circuit operated from a single +5V supply. The bridge provides a small differential voltage riding on an input common-mode voltage.

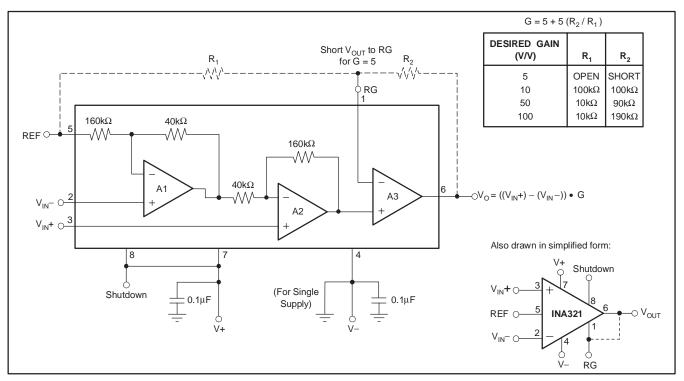


Figure 1. Basic Connections

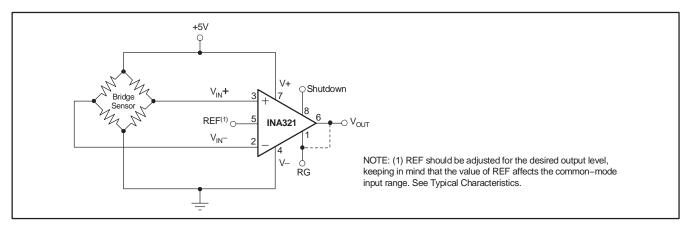


Figure 2. Bridge Amplifier of the INA321



SETTING THE GAIN

The ratio of R_2 to R_1 , or the impedance between pins 1, 5, and 6, determines the gain of the INA321. With an internally set gain of 5, the INA321 can be programmed for gains greater than 5 according to the following equation:

$$G = 5 + 5 (R_2/R_1)$$

The INA321 is designed to provide accurate gain, with gain error assured to be less than 0.1%. Setting gain with matching TC resistors will minimize gain drift. Errors from external resistors will add directly to the gain error, and may become dominant error sources.

INPUT COMMON-MODE RANGE

The upper limit of the common-mode input range is set by the common-mode input range of the second amplifier, A2, to 1.2V below positive supply. Under most conditions, the amplifier operates beyond this point with reduced performance. The lower limit of the input range is bounded by the output swing of amplifier A1, and is a function of the reference voltage according to the following equation:

$$V_{OA1} = 5/4 V_{CM} - 1/4 V_{REF}$$

(See Typical Characteristics for *Input Common-Mode Range vs Reference Voltage*).

REFERENCE

The reference terminal defines the zero output voltage level. In setting the reference voltage, the common-mode input of A3 should be considered according to the following equation:

$$V_{OA2} = V_{REF} + 5 (V_{IN} + - V_{IN} -)$$

For optimal operation, V_{OA2} should be less than V_{DD} – 1.2V.

The reference pin requires a low-impedance connection. As little as 160Ω in series with the reference pin will degrade the CMRR to 80dB. The reference pin may be used to compensate for the offset voltage (see *Offset Trimming* section). The reference voltage level also influences the common-mode input range (see *Common-Mode Input Range* section).

INPUT BIAS CURRENT RETURN

With a high input impedance of $10^{13}\Omega$, the INA321 is ideal for use with high-impedance sources. The input bias current of less than 10pA makes the INA321 nearly independent of input impedance and ideal for low-power applications.

For proper operation, a path must be provided for input bias currents for both inputs. Without input bias current paths, the inputs will *float* to a potential that exceeds common-mode range and the input amplifier will saturate. Figure 3 shows how bias current path can be provided in the cases of microphone applications, thermistor

applications, ground returns, and dc-coupled resistive

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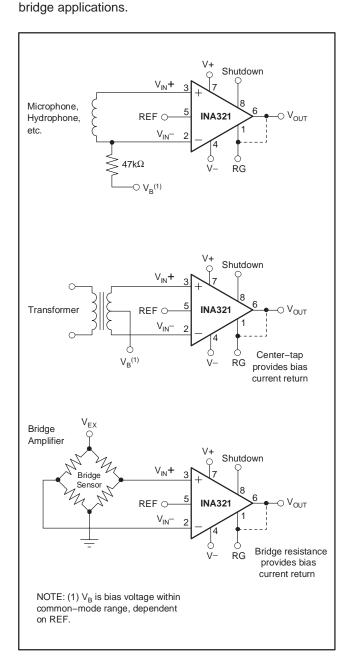


Figure 3. Providing an Input Common-Mode Path

When differential source impedance is low, the bias current return path can be connected to one input. With higher source impedance, two equal resistors will provide a balanced input. The advantages are lower input offset voltage due to bias current flowing through the source impedance and better high-frequency gain.



OUTPUT BUFFERING

The INA321 is optimized for a load impedance of $10k\Omega$ or greater. For higher output current the INA321 can be buffered using the OPA340, as shown in Figure 4. The OPA340 can swing within 50mV of the supply rail, driving a 600 Ω load. The OPA340 is available in the tiny MSOP-8 package.

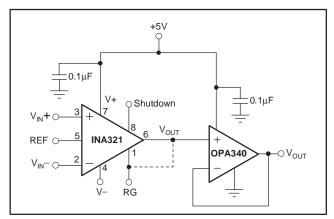


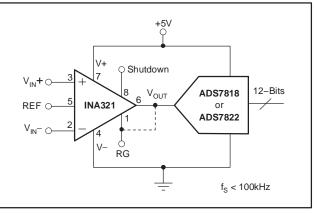
Figure 4. Output Buffering Circuit. Able to drive loads as low as 600Ω .

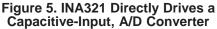
SHUTDOWN MODE

The shutdown pin of the INA321 is nominally connected to V+. When the pin is pulled below 0.8V on a 5V supply, the INA321 goes into sleep mode within nanoseconds. For actual shutdown threshold, see the Typical Characteristic curve, *Shutdown Voltage vs Supply Voltage*. Drawing less than 1 μ A of current, and returning from sleep mode in microseconds, the shutdown feature is useful for portable applications. Once in sleep-mode, the amplifier has high output impedance, making the INA321 suitable for multiplexing.

RAIL-TO-RAIL OUTPUT

A class AB output stage with common-source transistors is used to achieve rail-to-rail output for gains of 10 or greater. For resistive loads greater than $25k\Omega$, the output voltage can swing to within a few millivolts of the supply rail while maintaining low gain error. For heavier loads and over temperature, see the Typical Characteristic curve, *Output Voltage Swing vs Output Current*. The INA321's low output impedance at high frequencies makes it suitable for directly driving Capacitive Digital-to-Analog (CDAC) input A/D converters, as shown in Figure 5.





OFFSET TRIMMING

The INA321 is laser-trimmed for low offset voltage. In the event that external offset adjustment is required, the offset can be adjusted by applying a correction voltage to the reference terminal. Figure 6 shows an optional circuit for trimming offset voltage. The voltage applied to the REF terminal is added to the output signal. The gain from REF to V_{OUT} is +1. An op-amp buffer is used to provide low impedance at the REF terminal to preserve good common-mode rejection.

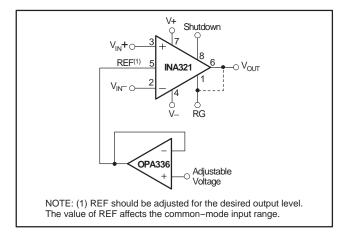


Figure 6. Optional Offset Trimming Voltage



INPUT PROTECTION

Device inputs are protected by ESD diodes that will conduct if the input voltages exceed the power supplies by more than 500mV. Momentary voltages greater than 500mV beyond the power supply can be tolerated if the current through the input pins is limited to 10mA. This is easily accomplished with input resistor R_{LIM} , as shown in Figure 7. Many input signals are inherently current-limited to less than 10mA; therefore, a limiting resistor is not required.

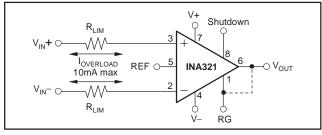


Figure 7. Input Protection

OFFSET VOLTAGE ERROR CALCULATION

The offset voltage (V_{OS}) of the INA321E is specified at a maximum of 500μ V with a +5V power supply and the common-mode voltage at V_S/2. Additional specifications for power-supply rejection and common-mode rejection are provided to allow the user to easily calculate worst-case expected offset under the conditions of a given application.

Power-Supply Rejection Ratio (PSRR) is specified in μ V/V. For the INA321, worst-case PSRR is 200 μ V/V, which means for each volt of change in power supply, the offset may shift up to 200 μ V. Common-Mode Rejection Ratio (CMRR) is specified in dB, which can be converted to μ V/V using the following equation:

CMRR (in μ V/V) = 10[(CMRR in dB)/-20] • 106

For the INA321, the worst-case CMRR over the specified common-mode range is 90dB (at G = 25) or about 30μ V/V. This means that for every volt of change in common-mode, the offset will shift less than 30μ V.

These numbers can be used to calculate excursions from the specified offset voltage under different application conditions. For example, an application might configure the amplifier with a 3.3V supply with 1V common-mode. This configuration varies from the specified configuration, representing a 1.7V variation in power supply (5V in the offset specification versus 3.3V in the application) and a 0.65V variation in common-mode voltage from the specified $V_S/2$. SBOS168D – DECEMBER 2000 – REVISED JANUARY 2006

Calculation of the worst-case expected offset would be as follows:

 $V_{OS} = 0.5mV + (1.7V \cdot 200\mu V) + (0.65V \cdot 30\mu V)$ = ±0.860mV

However, the typical value will be smaller, as seen in the Typical Characteristics.

FEEDBACK CAPACITOR IMPROVES RESPONSE

For optimum settling time and stability with high-impedance feedback networks, it may be necessary to add a feedback capacitor across the feedback resistor, R_F , as shown in Figure 8. This capacitor compensates for the zero created by the feedback network impedance and the INA321's RG-pin input capacitance (and any parasitic layout capacitance). The effect becomes more significant with higher impedance networks. Also, R_X and C_L can be added to reduce high-frequency noise.

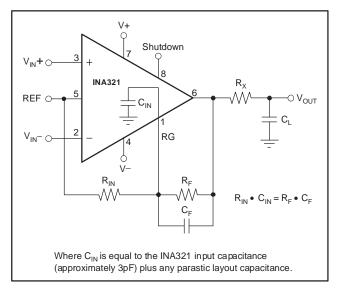


Figure 8. Feedback Capacitor Improves Dynamic Performance

It is suggested that a variable capacitor be used for the feedback capacitor since input capacitance may vary between instrumentation amplifiers, and layout capacitance is difficult to determine. For the circuit shown in Figure 8, the value of the variable feedback capacitor should be chosen by the following equation:

$$\mathsf{R}_{\mathsf{IN}} \bullet \mathsf{C}_{\mathsf{IN}} = \mathsf{R}_{\mathsf{F}} \bullet \mathsf{C}_{\mathsf{F}}$$

where C_{IN} is equal to the INA321's RG-pin input capacitance (typically 3pF) plus the layout capacitance. The capacitor can be varied until optimum performance is obtained.



APPLICATION CIRCUITS Medical ECG Applications

Figure 9 shows the INA321 configured to serve as a low-cost ECG amplifier, suitable for moderate accuracy heart-rate applications such as fitness equipment. The input signals are obtained from the left and right arms of the patient. The common-mode voltage is set by two $2M\Omega$ resistors. This potential, through a buffer, provides an

optional right leg drive. Filtering can be modified to suit application needs by changing the capacitor value of the output filter.

Low-Power, Single-Supply Data Acquisition Systems

Refer to Figure 5 to see the INA321 configured to drive an ADS7818. Functioning at frequencies of up to 500kHz, the INA321 is ideal for low-power data acquisition.

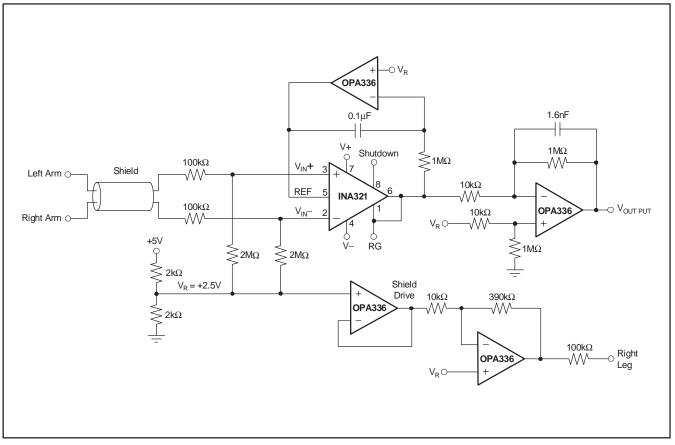


Figure 9. Simplified ECG Circuit for Medical Applications



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
INA2321EA/250	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
INA2321EA/250G4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
INA2321EA/2K5	ACTIVE	TSSOP	PW	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
INA2321EA/2K5G4	ACTIVE	TSSOP	PW	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
INA321E/250	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAC	GLevel-2-260C-1 YEAR	
INA321E/250G4	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAC	GLevel-2-260C-1 YEAR	
INA321E/2K5	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAC	GLevel-2-260C-1 YEAR	
INA321E/2K5G4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAC	GLevel-2-260C-1 YEAR	
INA321EA/250	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAC	GLevel-2-260C-1 YEAR	
INA321EA/250G4	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAC	GLevel-2-260C-1 YEAR	
INA321EA/2K5	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAC	GLevel-2-260C-1 YEAR	
INA321EA/2K5G4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAC	GLevel-2-260C-1 YEAR	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

PACKAGE OPTION ADDENDUM



www.ti.com

20-Oct-2011

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and package, or 2) lead-based die adhesive used between the die and pa

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION

REEL DIMENSIONS

TEXAS INSTRUMENTS





TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
INA2321EA/250	TSSOP	PW	14	250	180.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
INA2321EA/2K5	TSSOP	PW	14	2500	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
INA321E/250	MSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
INA321E/2K5	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
INA321EA/250	MSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
INA321EA/2K5	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

1-Dec-2011



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
INA2321EA/250	TSSOP	PW	14	250	210.0	185.0	35.0
INA2321EA/2K5	TSSOP	PW	14	2500	346.0	346.0	29.0
INA321E/250	MSOP	DGK	8	250	210.0	185.0	35.0
INA321E/2K5	MSOP	DGK	8	2500	346.0	346.0	29.0
INA321EA/250	MSOP	DGK	8	250	210.0	185.0	35.0
INA321EA/2K5	MSOP	DGK	8	2500	346.0	346.0	29.0

DGK (S-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.

- D Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
- E. Falls within JEDEC MO-187 variation AA, except interlead flash.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



A. An integration of the information o

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153



LAND PATTERN DATA



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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